

Features

- Glass passivated chip junction
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Solder dip 260°C, 10s
- Halogen-free according to IEC 61249-2-21 definition
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0



DO-214AB(SMC)

Applications

- For use of general purpose rectification in lighting, cellular phone, portable device, and power supplies.

(T

$T_A=25^\circ\text{C}$ unless otherwise noted)

Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at TL (See Fig.1)	$I_{F(AV)}$	3.0						A	
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	100						A	
Rating for Fusing ($t < 8.3\text{ms}$)	I_t	41.7						A sec	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to + 150						$^\circ\text{C}$	

($T_A=25^\circ\text{C}$ unless otherwise noted)

Maximum Instantaneous Forward Voltage	$I_F=3\text{A}, T_A=25$	V	1.15						Volts	
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25$	I	10.0						μA	
	$T_A=125$		250							
Typical Junction Capacitance	4.0 V, 1 MHz	C	60						pF	
Typical Reverse Recovery Time	$I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$	rr	1.8						μs	
Typical Thermal Resistance	Junction to Ambient	θ_{JA}	65						$^\circ\text{C}/\text{W}$	
	Junction to Case	θ_{JC}	10							
	Junction to Lead	θ_{JL}	15							

Note:

1. The thermal resistance from junction to ambient, case or lead, mounted on P.C.B with 8.0×8.0mm copper pads, 2 OZ, FR4 PCB

Surface Mount Glass Passivated Standard Rectifiers
 Reverse Voltage 50V to 1000V Forward Current 3.0A

Ratings and Characteristics Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

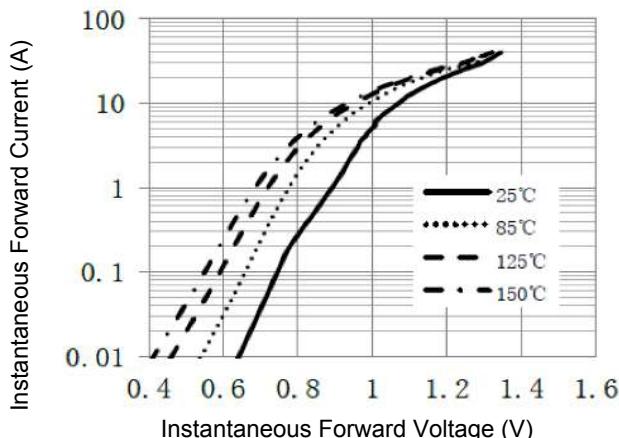


Figure 1. Typical Instantaneous Forward Characteristics

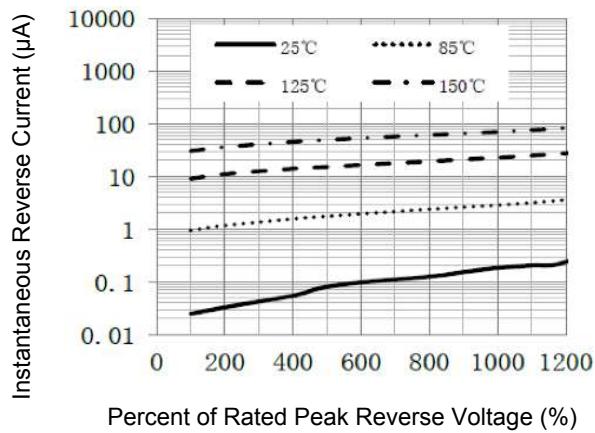


Figure 2. Typical Reverse Characteristics

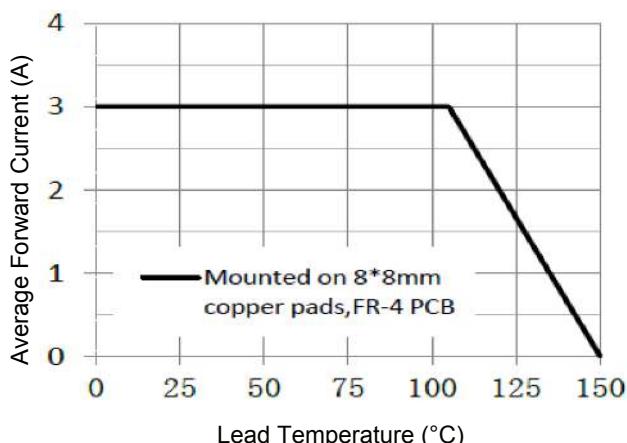


Figure 3. Forward Current Derating Curve

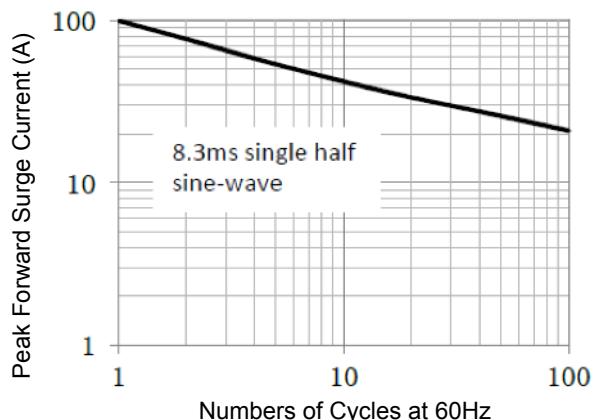


Figure 4. Maximum Non-Repetitive Forward Surge Current

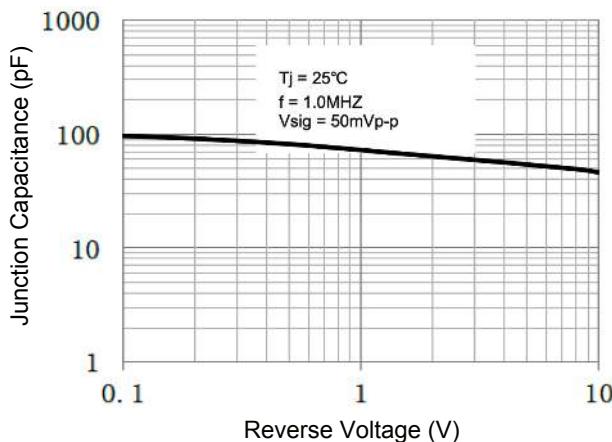
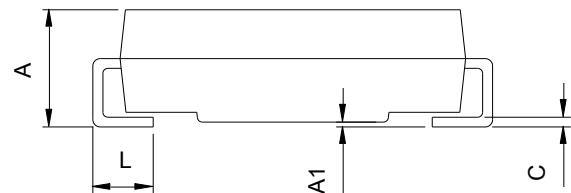
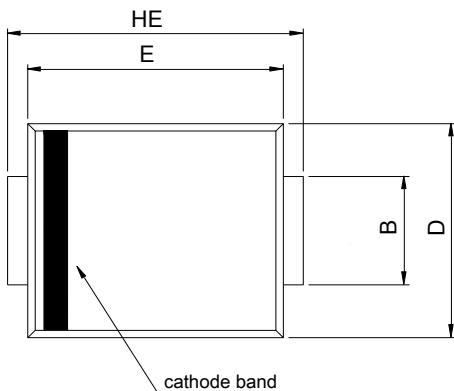


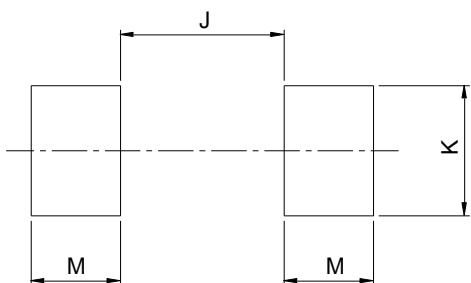
Figure 5. Typical Junction Capacitance

Package Outline Dimensions (SMC)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	2.00	2.62	0.079	0.103
A1	0.00	0.20	0.000	0.008
B	2.90	3.20	0.114	0.126
C	0.15	0.31	0.006	0.012
D	5.58	6.22	0.220	0.245
E	6.60	7.15	0.260	0.281
HE	7.75	8.15	0.305	0.321
L	0.76	1.60	0.030	0.063

Recommended Pad Layout



SMC Recommended Pad Layout (Reference ONLY)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	4.60	-	0.181
K	3.20	-	0.126	-
M	2.00	-	0.079	-